

ABSTRACT OF THE DISCLOSURE

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5 A process solution applying apparatus comprising a
substrate holding mechanism for holding a substrate, a
process solution supplying system for applying process
solution in a prescribed amount to the substrate held
by the substrate holding mechanism, the process
solution supplying system having a supplying mechanism
for changing a rate at which the process solution is
supplied, and a substrate rotating mechanism for
10 rotating the substrate holding mechanism, thus rotating
the substrate at a predetermined speed to spread the
process solution by virtue of centrifugal force and to
coat the substrate with the process solution.